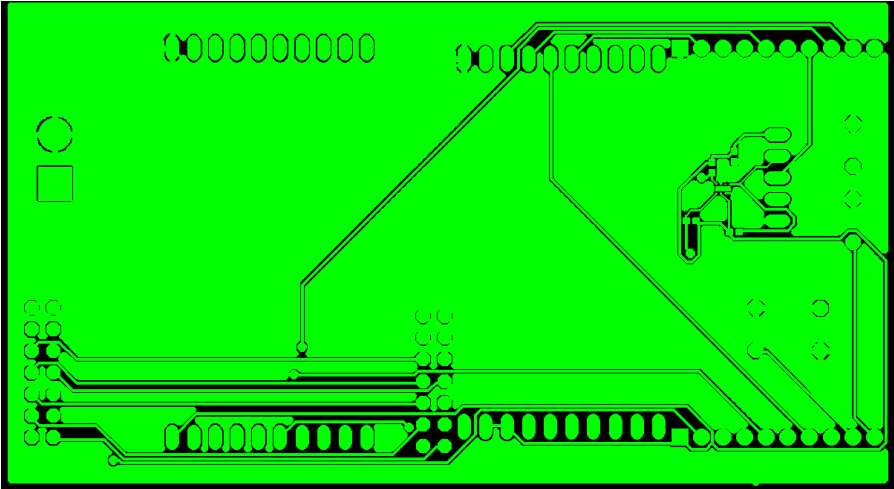
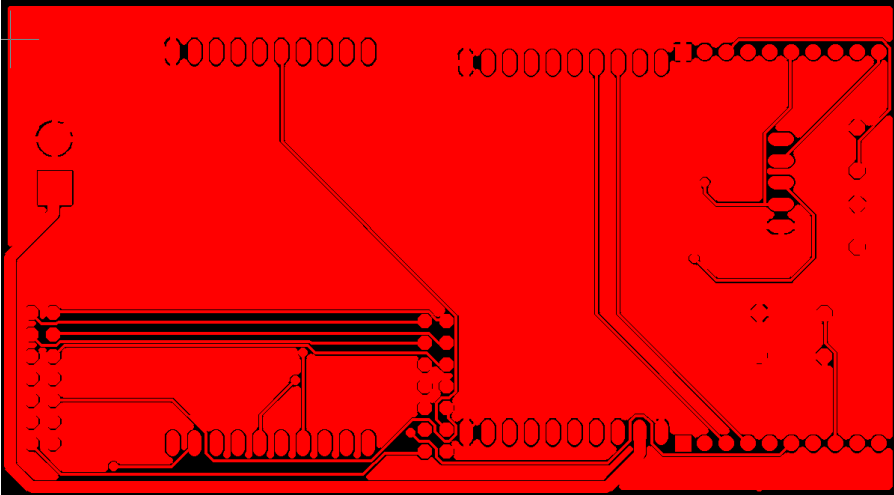


TIDM-KNXTHERMOSTAT Layer Plots

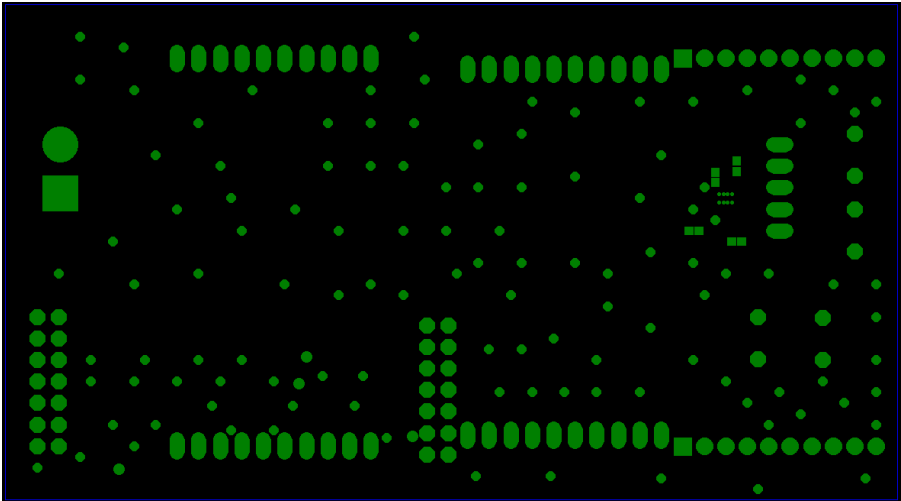
Copper Top



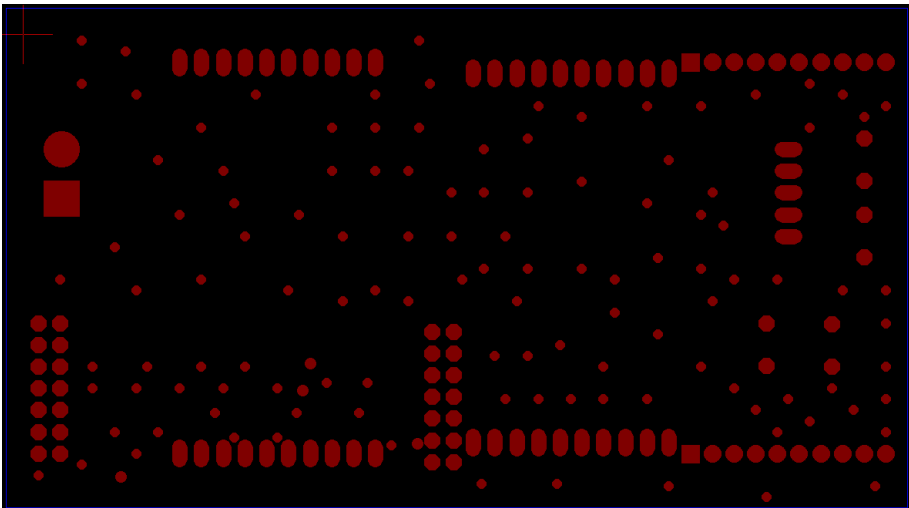
Copper Bottom



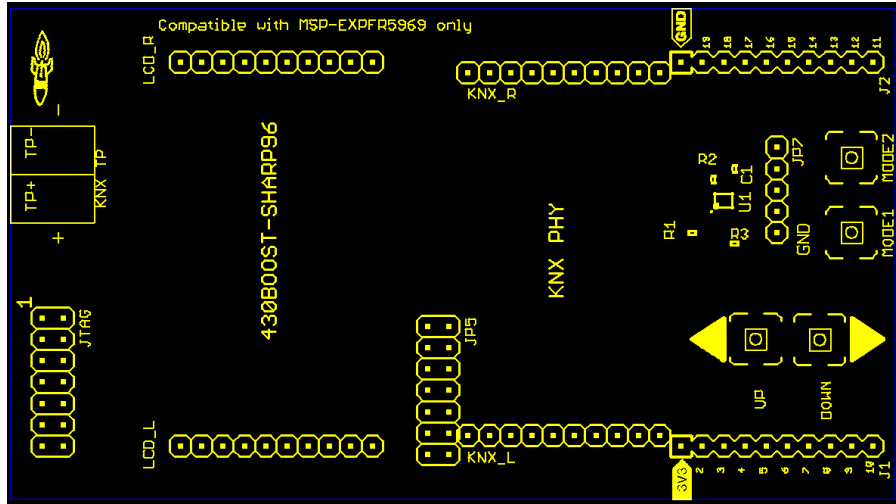
Soldermask top



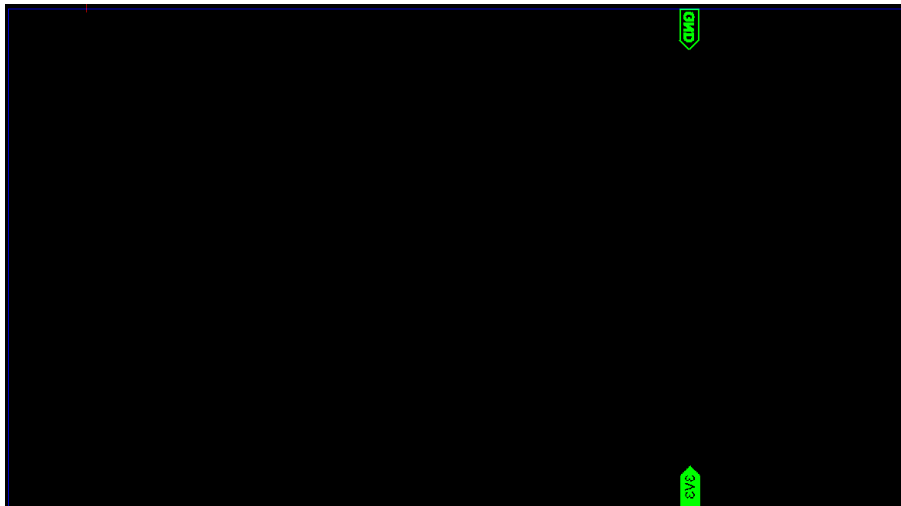
Soldermask bottom



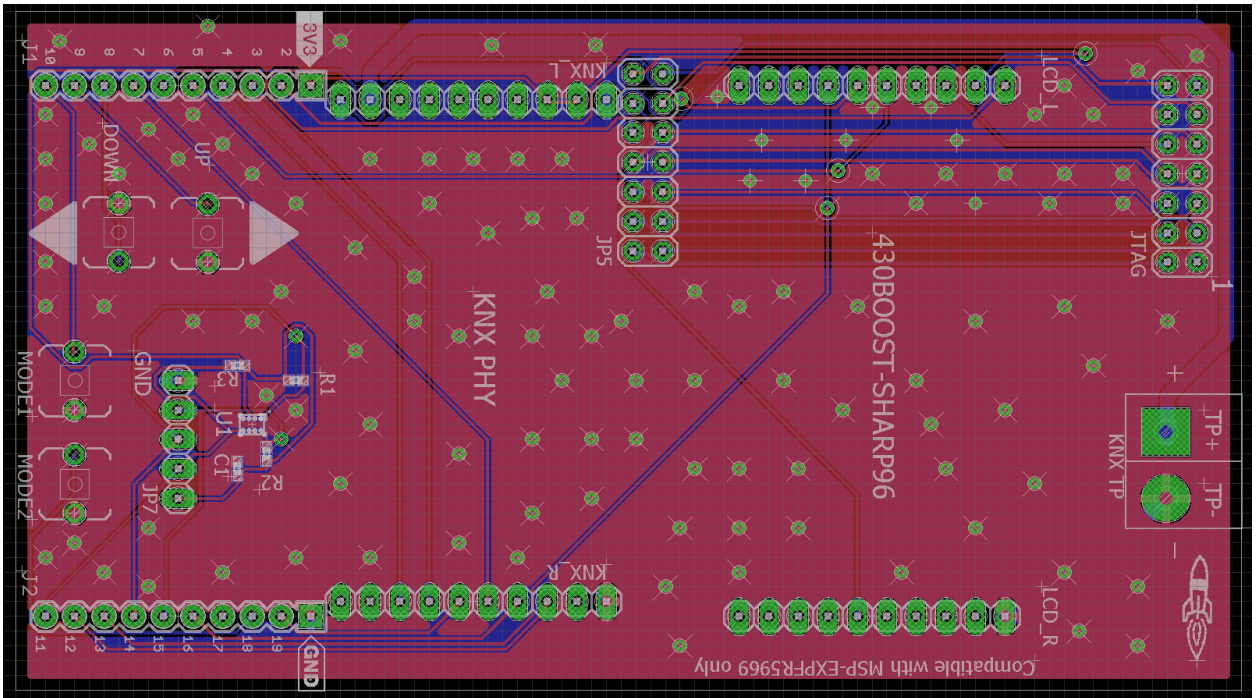
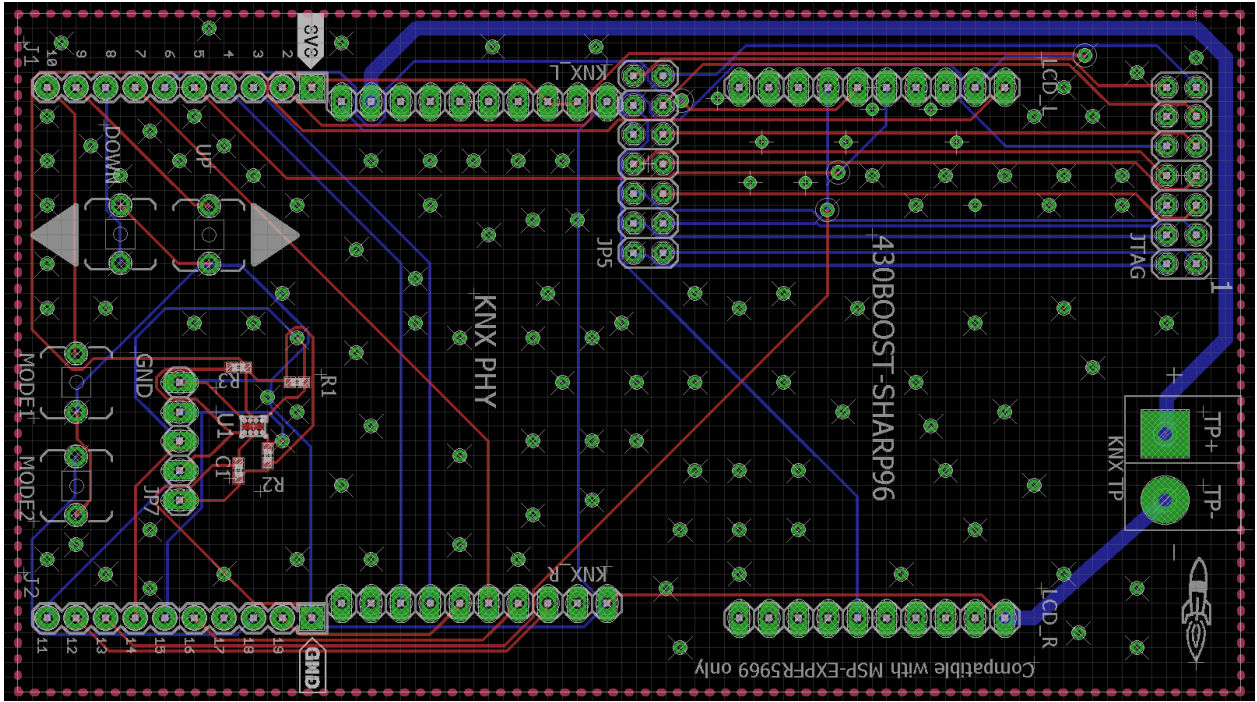
Silkscreen Top



Silkscreen Bottom



Eagle Layout



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